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CPY - KYOX

DC - A14 A26 A85 E33 E34 P73 P81

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MC - A08-M09C A09-A02 A12-L03 A12-W03 E33-C E34-D03

M3 - [01] A220 A940 C106 C108 C530 C730 C801 C802 C803 C805 C807 M411 M781

M903 M904 M910 Q130; R01278-U; 1327-U 0502-U

- [02] A111 A940 C108 C316 C540 C730 C801 C802 C803 C804 C805 M411 M781

M903 M904 M910 Q130; R01744-U; 1327-U 0502-U

PA - (KYOX) KYOWA GAS CHEM IND

PN - JP2194058 A 19900731 DW199036 000pp

- JP2512544B2 B2 19960703 DW199631 C08L101/00 004pp

PR - JP19890012736 19890121

XA - C1990-118041

XIC - B32B-007/02 ; C08K-007/16 ; C08L-101/00 ; G02B-005/02

AB - J02194058 Photodiffusion polymer prepn. comprises dispersing silicon resin particles (1) with average particle dia of 1-6 micro m in clear polymer (2) and opt adding clear inorganic particle materials (3) with average particle dia of 1-7 micro m. Pref. (1) is finely divided cured silicone resin eg polymethyl silsesquioxane prepd by building-up process, amts of 5 wt. pts. per 100 wt. pts. of resin of 8-30 g/m2 and (2) is methyl(meth)acrylate. (3) is Na2SO4, CaCO3 etc added to

increase whiteness and amts 0.3-1 wt. pts. per 100 wt. pts. of resin.
- USE ADVANTAGE - Illumination cover, illuminating signboard, display or glazing; non-transparent due to having haze value of 90% even though total transmittance is almost 86%. since dispersing finely divided silicon resin in clear resin. (5pp Dwg.No.0/0)

CN - R01278-U R01744-U

DRL - 1327-U 0502-U

IW - PHOTO DIFFUSION POLYMER ILLUMINATE PREPARATION DISPERSE SILICON RESIN
PARTICLE CLEAR POLYMER ADD CLEAR INORGANIC PARTICLE MATERIAL

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NC - 001

OPD - 1989-01-21

ORD - 1990-07-31

PAW - (KYOX) KYOWA GAS CHEM IND

TI - Photo-diffusion polymer, for illumination, etc. - is prepd. by dispersing silicon resin particles in clear polymer and adding clear inorganic particle material

A1: 905-915
KS-Paul.

1-6 mic
US equivalent
Inexpensive
5%
among 90-1
A1000 2